

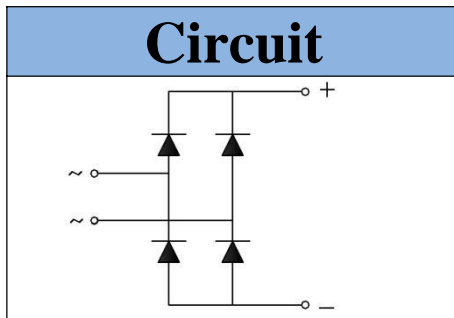


Glass Passivated Single Phase Bridge Rectifiers

Reverse Voltage 200 to 1000V
Forward Current 35 Amp

Features

- Glass passivated die construction
- Ideal for printed circuit boards
- High surge current capability
- High temperature soldering guaranteed: 265°C /10 seconds, 0.375" (9.5mm) lead length, 5lbs. (2.3kg) tension



Mechanical Data

Case: Molded plastic case
Terminals: Plated leads solderable per MIL-STD-750, Method 2026
Polarity: Marked on Body
Mounting Position: Any

Bridge Type

| TYPE | VRRM | VRSM |
|-----------|-------|-------|
| KBPC 3502 | 200V | 300V |
| KBPC 3504 | 400V | 500V |
| KBPC 3506 | 600V | 700V |
| KBPC 3508 | 800V | 900V |
| KBPC 3510 | 1000V | 1100V |

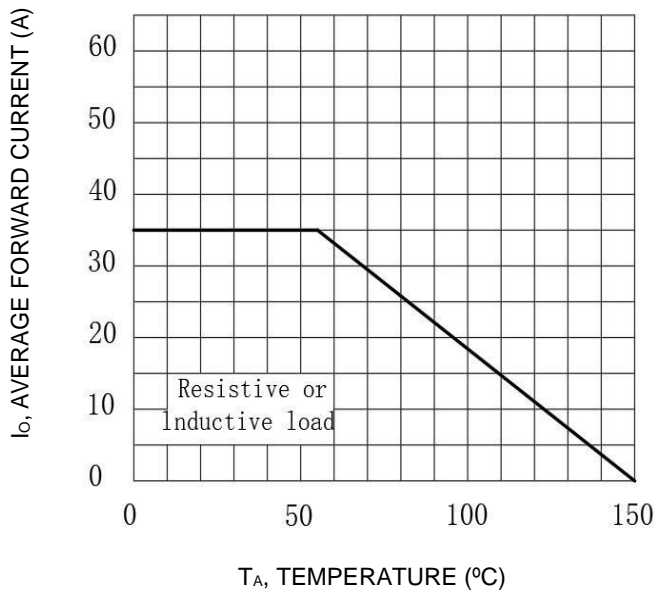
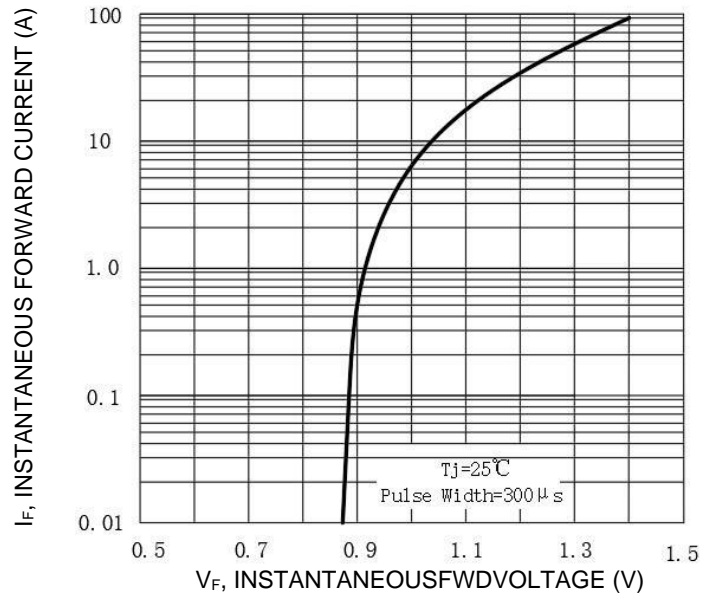
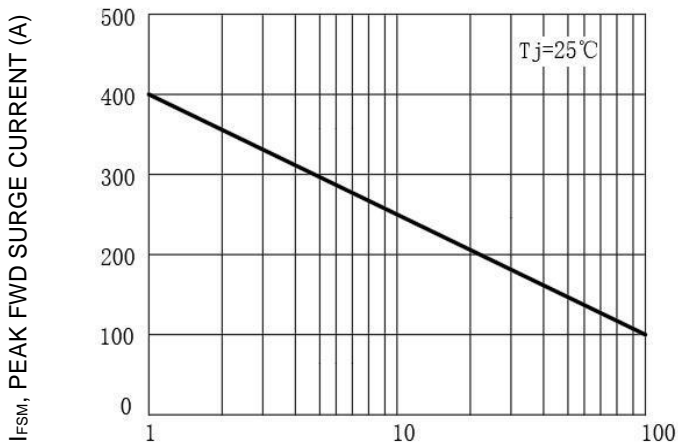
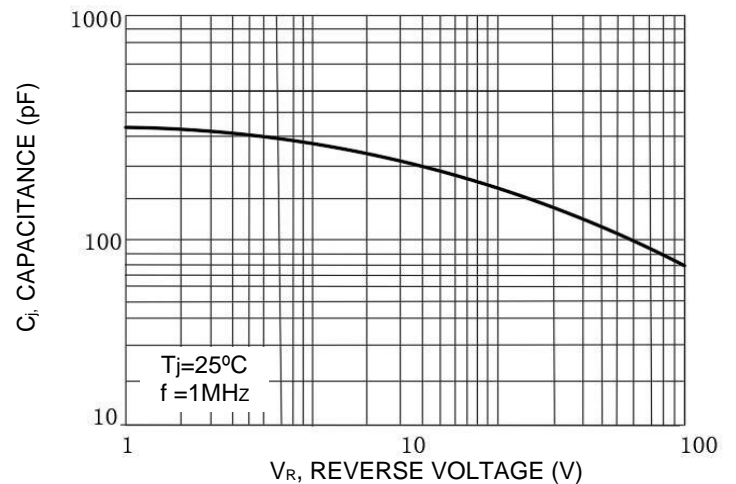
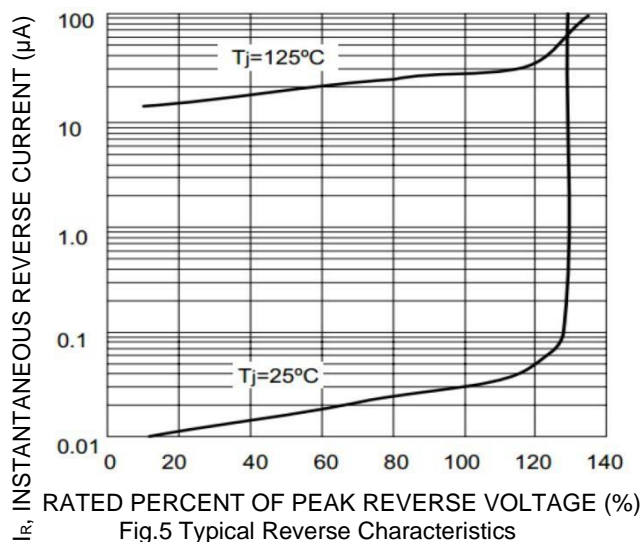
Maximum Ratings and Thermal Characteristics (TA = 25°C unless otherwise noted)

| Symbol | Conditions | Values | Units |
|------------------|--------------------------------------------------------------------------------------------|-------------|------------------|
| I(AV) | Maximum average forward output rectified current Tc =55°C | 35 | A |
| IFSM | Peak forward surge current single half sine-wave superimposed on rated load (JEDEC Method) | 400 | A |
| I ² t | Rating for fusing (t<10ms) | 800 | A ² s |
| Visol | a.c.50HZ;r.m.s.;1min | 2500 | V |
| RθJC | Maximum thermal resistance per leg (1) | 1.6 | °C/W |
| TOR | Mounting Torque (Recommended torque:0.5 N.m) | 2 | N.m |
| Tj, TSTG | Operating Junction and storage temperature range | -55 to +150 | °C |
| Weight | Approximate Weight | 18 | g |

Electrical Characteristics (TA = 25°C unless otherwise noted)

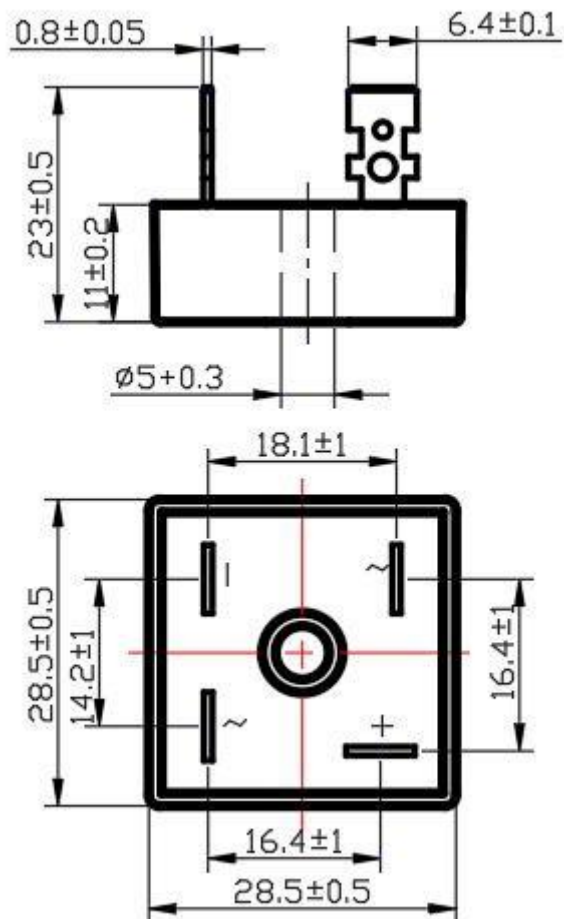
| Symbol | Conditions | Values | Units |
|----------------|--------------------------------------------------------------------------------------------|------------|-------|
| V _F | Maximum Instantaneous Forward Voltage per leg I _{FM} =17.5A | 1.1 | V |
| I _R | Maximum DC reverse current at rated DC blocking voltage per leg TA = 25°C TA = 125°C | 5.0 500 | μA |

Notes: (1) Junction to case with heatsink
 (2) Recommended mounting position is to bolt down on heatsink with silicone thermal compound for maximum heat transfer with #6 screw

Performance Curves

Fig.1 Forward Current Derating Curve

Fig.2 Typical Forward Characteristics, per element

Fig.3 Max Non-Repetitive Surge Current

Fig.4 Typical Junction Capacitance per Element

Fig.5 Typical Reverse Characteristics

Package Outline Information

CASE: KBPC



Dimensions in inches (mm)